

SOT1397-6

WLCSP20, wafer level chip-scale package; 20 bumps; 1.70 mm x 2.16 mm x 0.525 mm body (backside coating included)

19 January 2017

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	WLCSP20
Package type industry code	WLCSP20
Package style descriptive code	WLCSP (wafer level chip-size package)
Mounting method type	S (surface mount)
Issue date	19-1-2017
Manufacturer package code	SOT1397

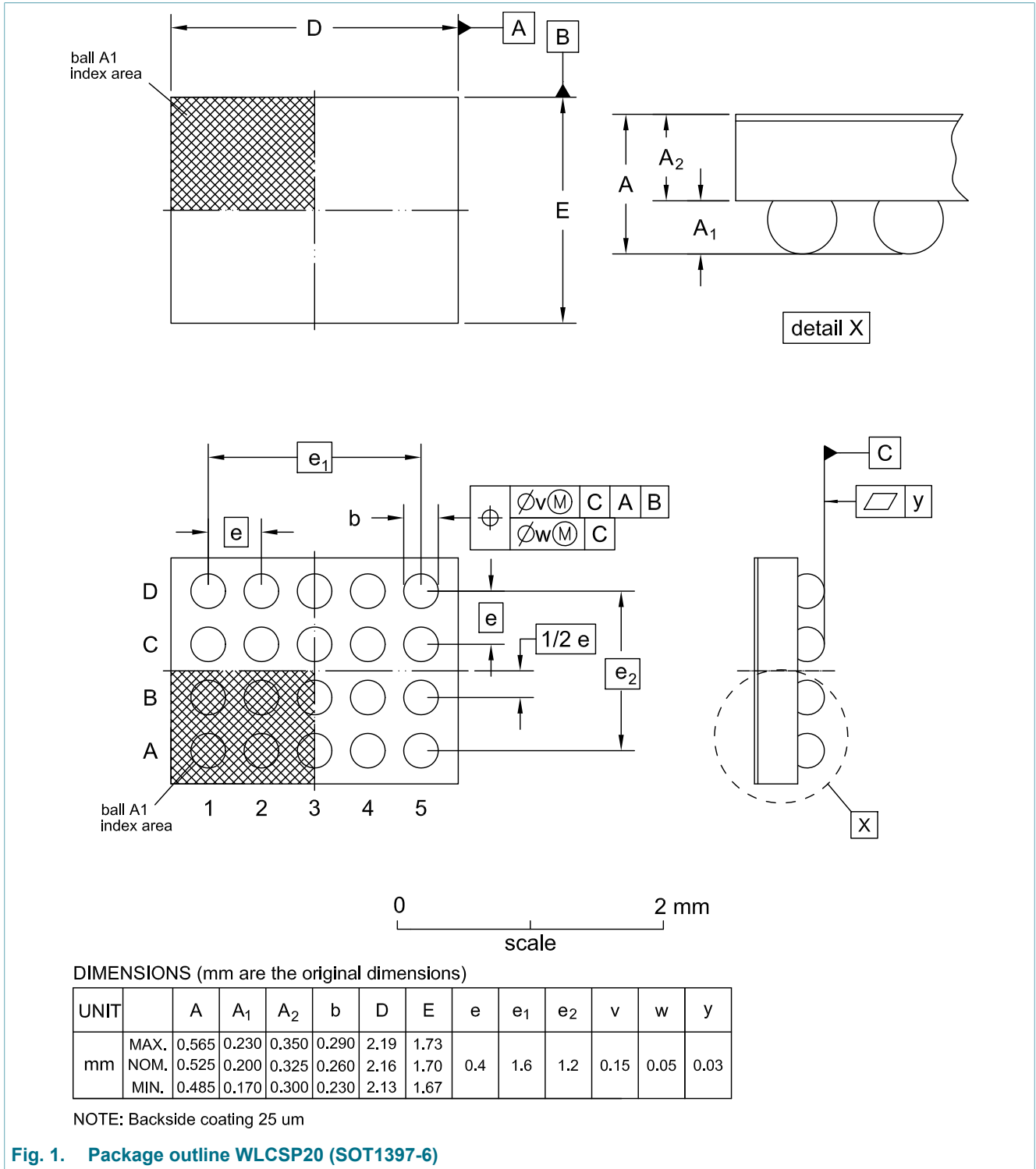
Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	2.13	-	2.16	2.19	mm
E	package width	1.67	-	1.7	1.73	mm
A	seated height	0.485	-	0.525	0.565	mm
A ₂	package height	0.3	-	0.325	0.35	mm
e	nominal pitch	-	-	0.4	-	mm
n ₂	actual quantity of termination	-	-	20	-	



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2. Package outline



WLCSP20, wafer level chip-scale package; 20 bumps; 1.70 mm x 2.16 mm x 0.525 mm body (backside coating included)

3. Legal information

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